ABSTRACT OF THE INVENTION

A sprayable adhesive composition having a viscosity within the range of 0.5 Pa.s to 5.0 Pa.s, containing at least one colored filler present in an amount up to 50% by weight of the adhesive composition, is suitable for marking identifications or fiducials on semiconductor dies or wafers. The preferred resins include epoxy resins or combinations of an electron donor resin and an electron acceptor resin.

period
Same as PGPUB.
SMH
12-08-2006

US 20050082338A1

(19) **United States**

(12) **Patent Application Publication**

(10) **Pub. No.: US 2005/0082338 A1**

(43) **Pub. Date: Apr. 21, 2005**

He et al.

(54) **SPRAYABLE ADHESIVE MATERIAL FOR LASER MARKING SEMICONDUCTOR WAFERS, DIES AND DEVICES**

(76) Inventors: **Xiping He**, Cerritos, CA (US); **Torey Tomaso**, Ladera Ranch, CA (US)

Correspondence Address:
Jane E. Gennaro
National Starch and Chemical
10 Finderne Avenue
Bridgewater, NJ 08807 (US)

(21) Appl. No.: **10/685,818**

(22) Filed: **Oct. 15, 2003**

Publication Classification

(51) **Int. Cl.**[7] **B23K 1/00**

(52) **U.S. Cl.** **228/101**

(57) **ABSTRACT**

A sprayable adhesive composition having a viscosity within the range of 0.5 Pa.s to 5.0 Pa.s, containing at least one colored filler present in an amount up to 50% by weight of the adhesive composition, is suitable for marking identifications or fiducials on semiconductor dies or wafers. The preferred resins include epoxy resins or combinations of an electron donor resin and an electron acceptor resin.